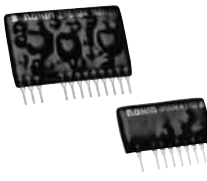
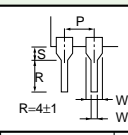


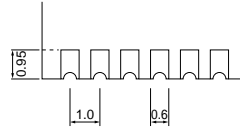


Available Package Types

Package type	Terminal size(mm)	Board length(mm)	Board width(mm)	Features												
	 <table border="1"> <tr> <td>P</td> <td>2.54</td> <td>1.8</td> </tr> <tr> <td>S</td> <td>(1.7)</td> <td>(1.6)</td> </tr> <tr> <td>W1</td> <td>0.5±0.1</td> <td>0.4±0.1</td> </tr> <tr> <td>W2</td> <td>1.3±0.2</td> <td>1.1±0.2</td> </tr> </table>	P	2.54	1.8	S	(1.7)	(1.6)	W1	0.5±0.1	0.4±0.1	W2	1.3±0.2	1.1±0.2	14Min. to 65Max.	7Min. to 38Max.	Small on-board space requirement permit-function-intensive equipment design. Epoxy coated packages are available to assure reliable use in industrial and automobile equipment.
P	2.54	1.8														
S	(1.7)	(1.6)														
W1	0.5±0.1	0.4±0.1														
W2	1.3±0.2	1.1±0.2														
		10Min. to 90Max.	7Min. to 70Max.	Available in the BW series. Typical applications include mother boards that use ROHM's composite assembly technology for additional space savings in these high density boards.												
		7Min. to 20Max.	7Min. to 20Max.	Tray delivery facilitates automatic mounting. Achieved super small high densities.												

Part No. Explanation

- When ordering, specify the part number.
- Check each code against the table shown below.
- Fill in from the left, leaving any extra boxes empty on the right.

B **P** **5** **0** **4** **1**

Part No.

BW	Glass epoxy substrate, chip components, terminalless
BX	Glass epoxy substrate, chip components, w/terminals
BP	General purpose, custom design acceptable
BK	Thin glass epoxy substrate, on-chip COM, MCM